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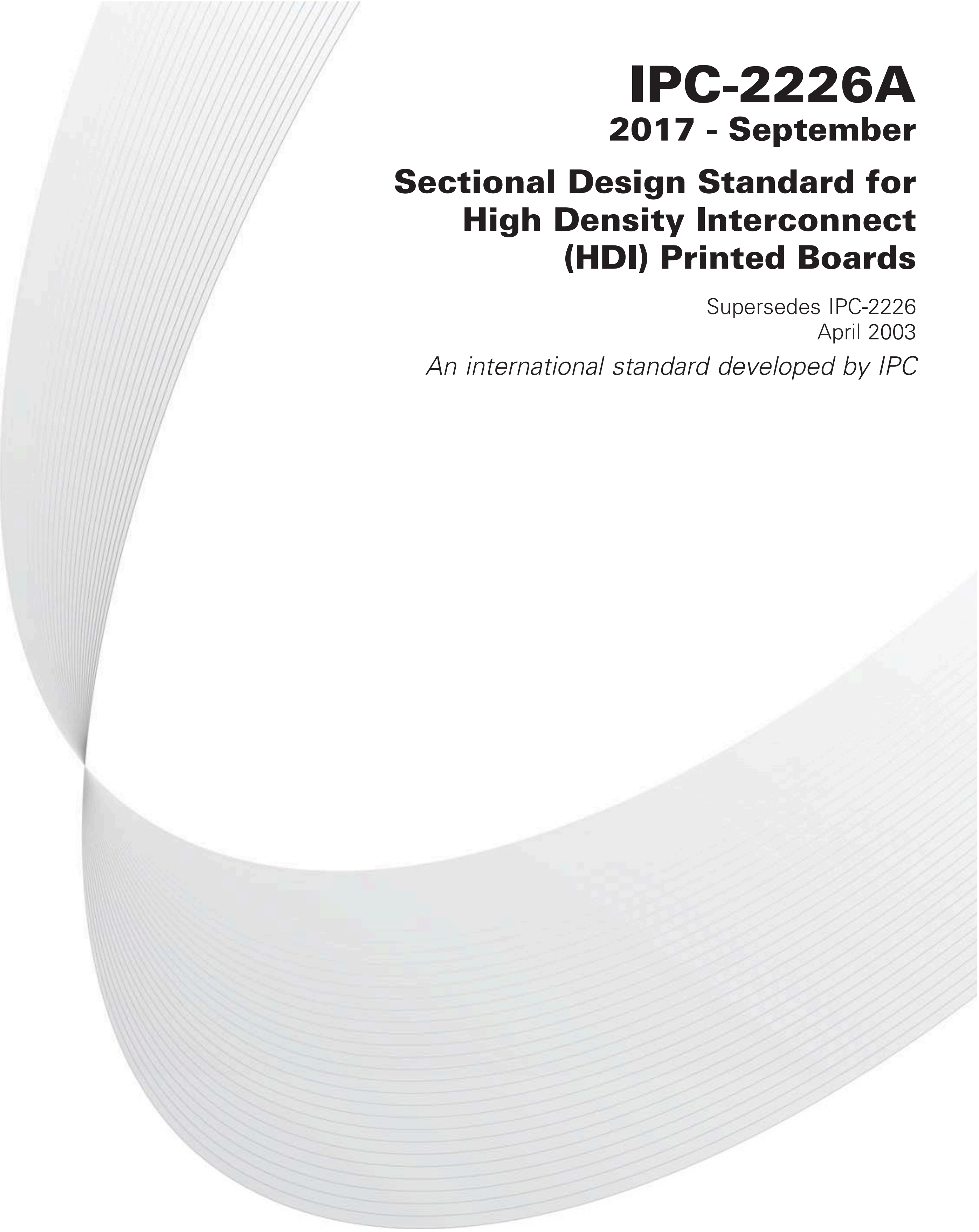
Sectional Design Standard for High Density Interconnect (HDI) Printed Boards

Supersedes IPC-2226
April 2003

An international standard developed by IPC



Association Connecting Electronics Industries

The Principles of Standardization

In May 1995 the IPC's Technical Activities Executive Committee (TAEC) adopted Principles of Standardization as a guiding principle of IPC's standardization efforts.

Standards Should:

- Show relationship to Design for Manufacturability (DFM) and Design for the Environment (DFE)
- Minimize time to market
- Contain simple (simplified) language
- Just include spec information
- Focus on end product performance
- Include a feedback system on use and problems for future improvement

Standards Should Not:

- Inhibit innovation
- Increase time-to-market
- Keep people out
- Increase cycle time
- Tell you how to make something
- Contain anything that cannot be defended with data

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Sectional Design Standard for High Density Interconnect (HDI) Printed Boards

Developed by the IPC-2221/2222 Task Group (D-31b) of the Rigid Printed Board Committee (D-30) of IPC

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Users of this publication are encouraged to participate in the development of future revisions.

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